

**Certification under 37 CFR 1.8(a)**

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with The United States Postal Service with sufficient postage as first class mail in an envelope addressed to The Assistant Commissioner of Patents, Washington, D.C. 20231 on January 18, 2001.

Richard J. Streit (Reg. No. 25765)

Name

Signature

DOCKET: CU-2417

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of: Takahiro IJIMA et al

Serial No.: 09/736,864

Group Art Unit:

Filed: December 14, 2000

Examiner:

For: Interconnection Substrate Having Metal Columns Covered by a Resin Film, and Manufacturing Method Thereof

THE ASSISTANT COMMISSIONER FOR PATENTS  
Washington, D.C. 20231

**TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT WITHIN THREE MONTHS OF FILING OR BEFORE MAILING OF FIRST OFFICE ACTION**

The information disclosure statement submitted herewith is being filed within three months of the filing date of the application or date of entry into the national stage of an international application or before the mailing date of the first Office Action on the merits, whichever event occurs last. 37 CFR 1.97(b).

Date: January 18, 2001

Signature of Attorney

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**INFORMATION DISCLOSURE STATEMENT**

Applicants submit herewith patents, publications or other information of which the applicants are aware, which may be material to the examination of this application and in respect of which there may be a duty to disclose under 37 CFR 1.56.

The filing of this information disclosure statement shall not be construed as a representation that a search has been made (37 CFR 1.97(g)), an admission that the information cited is, or is considered to be, material to patentability or that no other material information exists.

The filing of this information disclosure statement shall not be construed as an admission against interest in any manner. Notice of January 9, 1992, 1135 O.G. 13-25, at 25.

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The references submitted herein are listed on PTO-1449 form (modified) enclosed herewith. A copy of each reference listed is being furnished except any duplicate or cumulative patents or publications specified otherwise.

A translation of any foreign language reference, if any, is indicated in PTO-1449 form and being submitted herein if it is readily available. Otherwise it should be construed that such translation is not readily available.

Additional comments, if any, on the relevance of each reference listed are provided as follows:

Additional comments on the Japanese reference are provided as follows:

Japanese Laid-Open Patent Application No. 63-79330

A copy of English language abstract is attached.

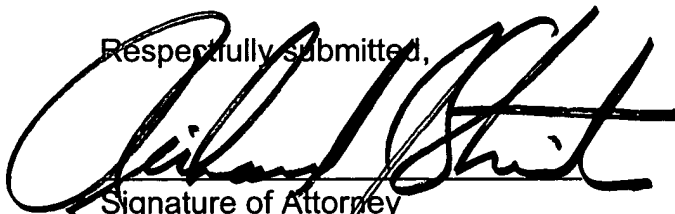
This patent document describes a metal pillar-shaped body 4 arranged on the surface of a mounting substrate 1. The metal pillar-shaped body 4 is connected to a projection electrode 5 of a semiconductor element 6. It should be noted that a film resist 2 is eliminated before mounting the semiconductor element 6 on the mounting substrate 1. The figure shows the film resist 2 only for the purpose of explanation. It should also be noted that, in our invention, a resin film is formed so as to cover a side surface of a metal column. However, in regard to this patent document, such a resin film is not formed.

The Statement is made on the basis of the information:

_____	supplied by the inventor(s);
<u>  X  </u>	supplied by an individual associated with the filing and prosecution
_____	of this application (37 CFR 1.56(c)); or
_____	in the attorney's file.

Date: January 18, 2001

Respectfully submitted,



Signature of Attorney

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